

AMENDMENTSIn the Claims:

1. (Currently Amended) A curable composition that forms comprises a continuous phase and a dispersoid at ambient temperatures, wherein
 - the continuous phase is a liquid at ambient temperatures and comprises (a) a compound having two or more epoxy groups in a molecule, [[and]]
 - the dispersoid comprises (b) a compound present as solid particles in a continuous phase at ambient temperatures and having two or more amino groups in a molecule, and
 - the compound having two or more amino groups in a molecule is an aromatic amine compound having a benzoxazole structure.
2. (Canceled)
3. (Previously Presented) The curable composition of claim 1, wherein the compound having two or more epoxy groups in a molecule is a liquid at ambient temperatures.
4. (Previously Presented) The curable composition of claim 1, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.
5. (Previously Presented) The curable composition of claim 1, wherein the solid particles have a volume average particle size of 0.05 – 50 μm .
- 6-7. (Canceled)
8. (Previously Presented) The curable composition of claim 3, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.
- 9-10. (Canceled)
11. (Previously Presented) The curable composition of claim 3, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .
12. (Canceled)

13. (Previously Presented) The curable composition of claim 4, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

14. (Canceled)

15. (Previously Presented) The curable composition of claim 8, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

16. (Canceled)